

## K3935-VB Datasheet

### N-Channel 650 V (D-S) Super Junction Power MOSFET

| PRODUCT SUMMARY                    |                 |      |
|------------------------------------|-----------------|------|
| $V_{DS}$ (V) at $T_J$ max.         | 650             |      |
| $R_{DS(on)}$ at 25 °C ( $\Omega$ ) | $V_{GS} = 10$ V | 0.19 |
| $Q_g$ Typ. (nC)                    | 106             |      |
| $Q_{gs}$ (nC)                      | 14              |      |
| $Q_{gd}$ (nC)                      | 33              |      |
| Configuration                      | Single          |      |

#### FEATURES

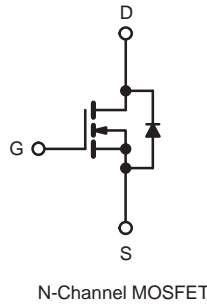
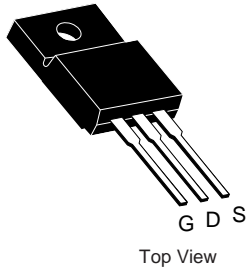
- Low figure-of-merit (FOM)  $R_{on} \times Q_g$
- Low input capacitance ( $C_{iss}$ )
- Reduced switching and conduction losses
- Ultra low gate charge ( $Q_g$ )
- Avalanche energy rated (UIS)



#### APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial

TO-220 FULLPAK




| ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted) |                  |                |              |
|---|------------------|----------------|--------------|
| PARAMETER   | SYMBOL           | LIMIT          | UNIT         |
| Drain-Source Voltage  | $V_{DS}$         | 650            | V            |
| Gate-Source Voltage   | $V_{GS}$         | $\pm 30$       |              |
| Continuous Drain Current ( $T_J = 150$ °C)                        | $V_{GS}$ at 10 V | $T_C = 25$ °C  | 20           |
|   |                  | $T_C = 100$ °C | 13           |
| Pulsed Drain Current <sup>a</sup>                                 |                  | $I_{DM}$       | 53           |
| Linear Derating Factor  |                  |                | 1.67/1.5/0.3 |
| Single Pulse Avalanche Energy <sup>b</sup>                        |                  | $E_{AS}$       | 360          |
| Maximum Power Dissipation   |                  | $P_D$          | 200          |
| Operating Junction and Storage Temperature Range                  |                  | $T_J, T_{stg}$ | -55 to +150  |
| Drain-Source Voltage Slope  |                  | $dV/dt$        | 50           |
| Reverse Diode $dV/dt$ <sup>d</sup>                                | $T_J = 125$ °C   |                | 3.1          |
| Soldering Recommendations (Peak Temperature) <sup>c</sup>         | for 10 s         |                | 300          |
|   |                  |                | °C           |

#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$  V, starting  $T_J = 25$  °C,  $L = 28.2$  mH,  $R_g = 25$   $\Omega$ ,  $I_{AS} = 4.5$  A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$ ,  $dI/dt = 100$  A/ $\mu$ s, starting  $T_J = 25$  °C.

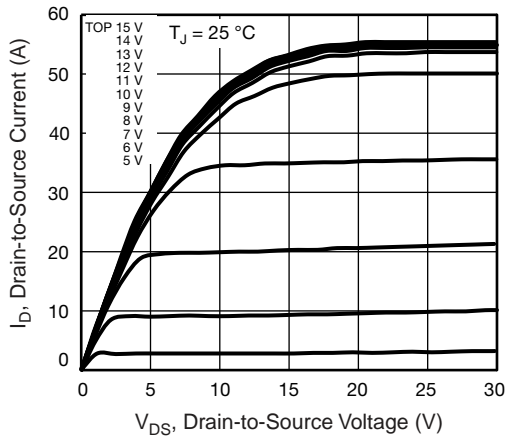
| THERMAL RESISTANCE RATINGS       |            |      |      |      |
|----------------------------------|------------|------|------|------|
| PARAMETER                        | SYMBOL     | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient      | $R_{thJA}$ | -    | 62   | °C/W |
| Maximum Junction-to-Case (Drain) | $R_{thJC}$ | -    | 0.5  |      |

| SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted) |                     |   |  |      |      |           |               |
|---|---------------------|---|--|------|------|-----------|---------------|
| PARAMETER   | SYMBOL              | TEST CONDITIONS   |  | MIN. | TYP. | MAX.      | UNIT          |
| <b>Static</b>   |                     |   |  |      |      |           |               |
| Drain-Source Breakdown Voltage  | $V_{DS}$            | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$   |  | 650  | -    | -         | V             |
| $V_{DS}$ Temperature Coefficient  | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}$ , $I_D = 1\text{ mA}$   |  | -    | 0.67 | -         | V/°C          |
| Gate-Source Threshold Voltage (N)   | $V_{GS(th)}$        | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$   |  | 2    | -    | 5         | V             |
| Gate-Source Leakage   | $I_{GSS}$           | $V_{GS} = \pm 20\text{ V}$  |  | -    | -    | $\pm 100$ | nA            |
|   |                     | $V_{GS} = \pm 30\text{ V}$  |  | -    | -    | $\pm 1$   | $\mu\text{A}$ |
| Zero Gate Voltage Drain Current   | $I_{DSS}$           | $V_{DS} = 520\text{ V}, V_{GS} = 0\text{ V}$  |  | -    | -    | 1         | $\mu\text{A}$ |
|   |                     | $V_{DS} = 520\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$   |  | -    | -    | 500       |               |
| Drain-Source On-State Resistance  | $R_{DS(on)}$        | $V_{GS} = 10\text{ V}$  | $I_D = 11\text{ A}$                        | -    | 0.19 | -         | $\Omega$      |
| Forward Transconductance  | $g_{fs}$            | $V_{DS} = 30\text{ V}, I_D = 11\text{ A}$   |  | -    | 7.0  | -         | S             |
| <b>Dynamic</b>  |                     |   |  |      |      |           |               |
| Input Capacitance   | $C_{iss}$           | $V_{GS} = 0\text{ V},$<br>$V_{DS} = 100\text{ V},$<br>$f = 1\text{ MHz}$  |  | -    | 2322 | -         | pF            |
| Output Capacitance  | $C_{oss}$           |   |  | -    | 105  | -         |               |
| Reverse Transfer Capacitance  | $C_{rss}$           |   |  | -    | 4    | -         |               |
| Effective Output Capacitance, Energy Related <sup>a</sup>                   | $C_{o(er)}$         | $V_{DS} = 0\text{ V to } 520\text{ V}, V_{GS} = 0\text{ V}$   |  | -    | 84   | -         | pF            |
| Effective Output Capacitance, Time Related <sup>b</sup>                     | $C_{o(tr)}$         |   |  | -    | 293  | -         |               |
| Total Gate Charge   | $Q_g$               | $V_{GS} = 10\text{ V}$  | $I_D = 11\text{ A}, V_{DS} = 520\text{ V}$ | -    | 71   | 106       | nC            |
| Gate-Source Charge  | $Q_{gs}$            |   |  | -    | 14   | -         |               |
| Gate-Drain Charge   | $Q_{gd}$            |   |  | -    | 33   | -         |               |
| Turn-On Delay Time  | $t_{d(on)}$         | $V_{DD} = 520\text{ V}, I_D = 11\text{ A},$<br>$V_{GS} = 10\text{ V}, R_g = 9.1\text{ }\Omega$  |  | -    | 22   | 44        | ns            |
| Rise Time   | $t_r$               |   |  | -    | 34   | 68        |               |
| Turn-Off Delay Time   | $t_{d(off)}$        |   |  | -    | 68   | 102       |               |
| Fall Time   | $t_f$               |   |  | -    | 42   | 84        |               |
| Gate Input Resistance   | $R_g$               | $f = 1\text{ MHz}, \text{ open drain}$  |  | -    | 0.78 | -         | $\Omega$      |
| <b>Drain-Source Body Diode Characteristics</b>                              |                     |   |  |      |      |           |               |
| Continuous Source-Drain Diode Current                                       | $I_S$               | MOSFET symbol showing the integral reverse p - n junction diode  |  | -    | -    | 21        | A             |
| Pulsed Diode Forward Current  | $I_{SM}$            |   |  | -    | -    | 53        |               |
| Diode Forward Voltage   | $V_{SD}$            | $T_J = 25\text{ }^\circ\text{C}, I_S = 11\text{ A}, V_{GS} = 0\text{ V}$  |  | -    | 0.9  | 1.2       | V             |
| Reverse Recovery Time   | $t_{rr}$            | $T_J = 25\text{ }^\circ\text{C}, I_F = I_S = 11\text{ A},$<br>$di/dt = 100\text{ A}/\mu\text{s}, V_R = 25\text{ V}$                                   |  | -    | 160  | -         | ns            |
| Reverse Recovery Charge   | $Q_{rr}$            |   |  | -    | 1.2  | -         | $\mu\text{C}$ |
| Reverse Recovery Current  | $I_{RRM}$           |   |  | -    | 14   | -         | A             |

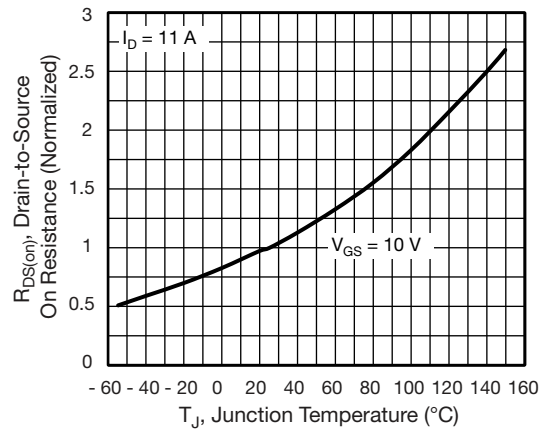
**Notes**

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .  
 b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

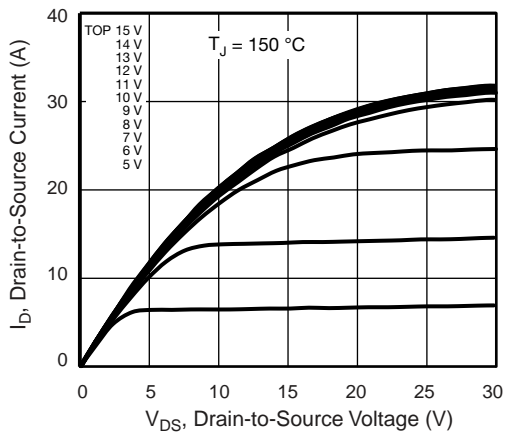
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



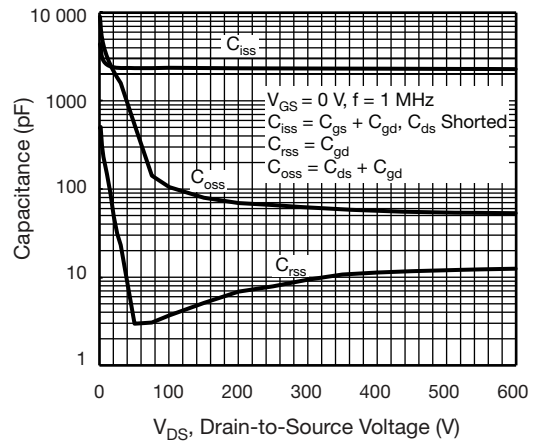
**Fig. 1 - Typical Output Characteristics**



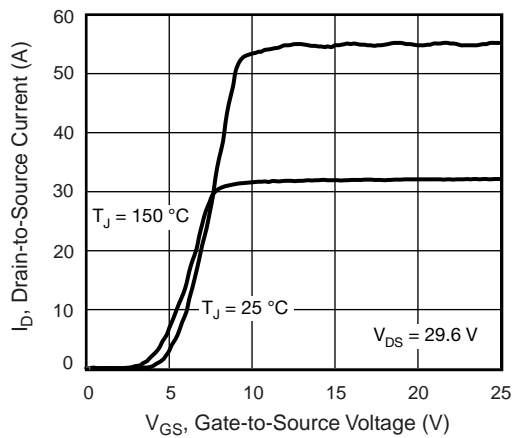
**Fig. 4 - Normalized On-Resistance vs. Temperature**



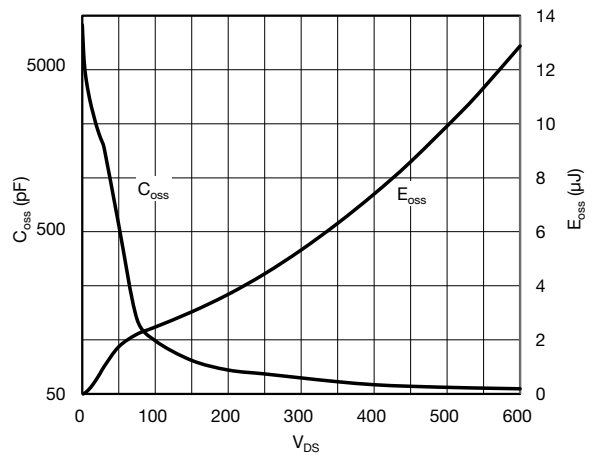
**Fig. 2 - Typical Output Characteristics**



**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**



**Fig. 3 - Typical Transfer Characteristics**



**Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$**

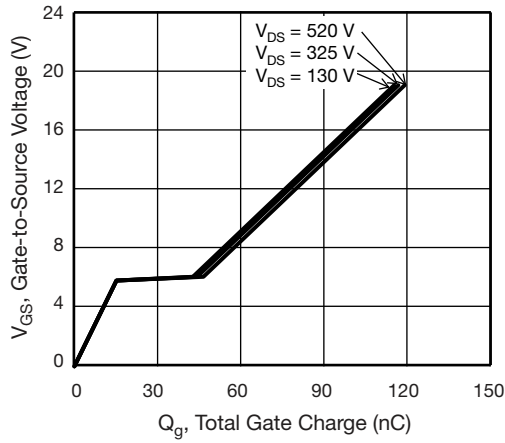


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

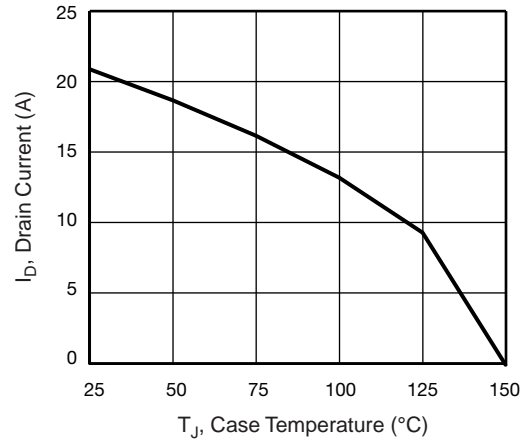


Fig. 10 - Maximum Drain Current vs. Case Temperature

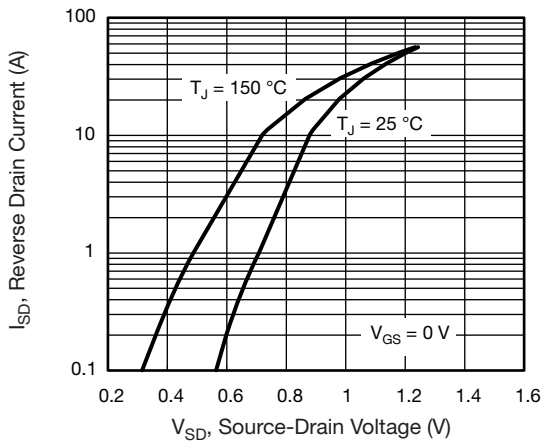


Fig. 8 - Typical Source-Drain Diode Forward Voltage



Fig. 11 - Temperature vs. Drain-to-Source Voltage

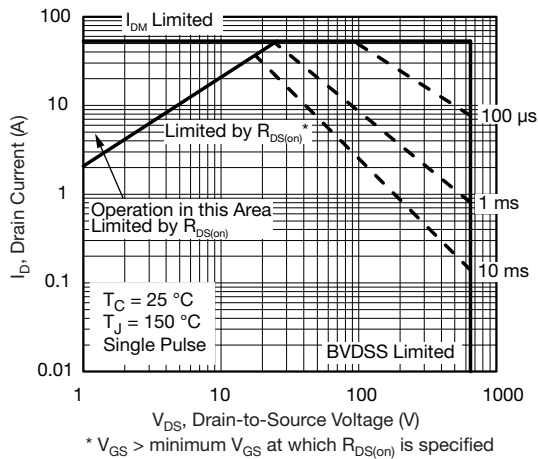


Fig. 9 - Maximum Safe Operating Area

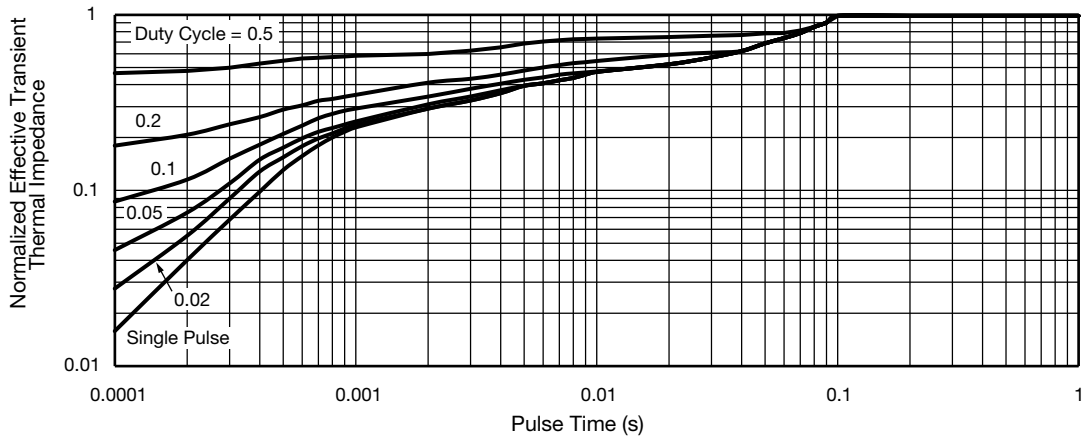


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

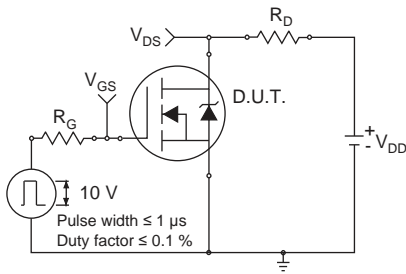


Fig. 13 - Switching Time Test Circuit

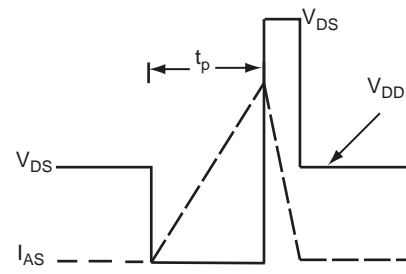


Fig. 16 - Unclamped Inductive Waveforms

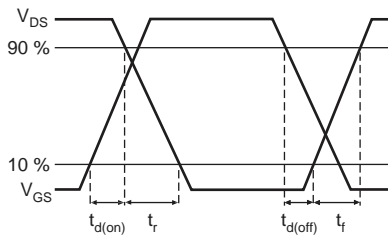


Fig. 14 - Switching Time Waveforms

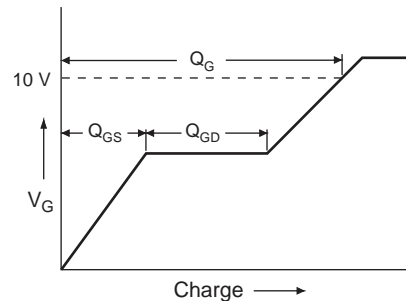


Fig. 17 - Basic Gate Charge Waveform

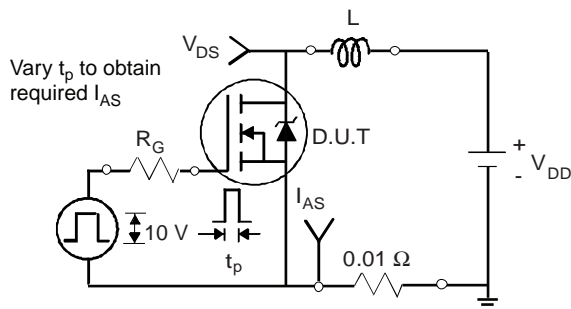


Fig. 15 - Unclamped Inductive Test Circuit

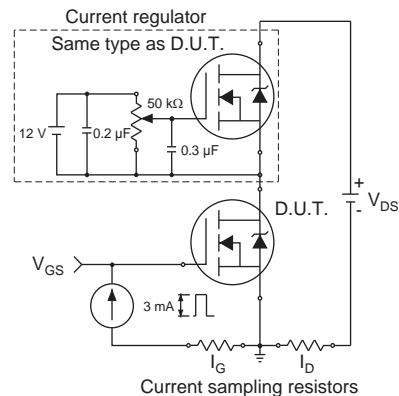
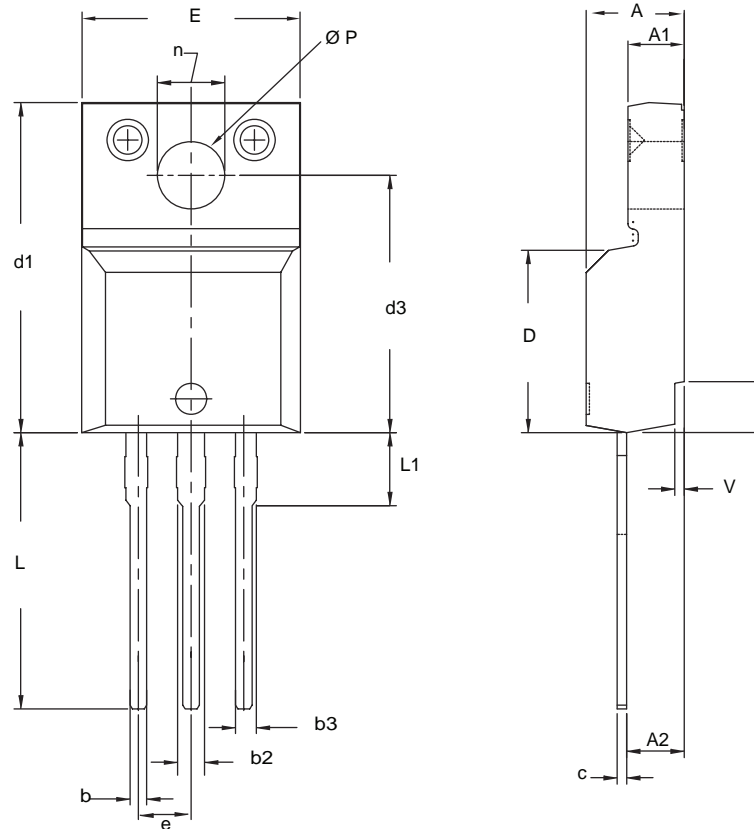


Fig. 18 - Gate Charge Test Circuit

**TO-220 FULLPAK (HIGH VOLTAGE)**

| DIM.   | MILLIMETERS |        | INCHES    |       |
|--|-------------|--------|-----------|-------|
|  | MIN.        | MAX.   | MIN.      | MAX.  |
| A  | 4.570       | 4.830  | 0.180     | 0.190 |
| A1   | 2.570       | 2.830  | 0.101     | 0.111 |
| A2   | 2.510       | 2.850  | 0.099     | 0.112 |
| b  | 0.622       | 0.890  | 0.024     | 0.035 |
| b2   | 1.229       | 1.400  | 0.048     | 0.055 |
| b3   | 1.229       | 1.400  | 0.048     | 0.055 |
| c  | 0.440       | 0.629  | 0.017     | 0.025 |
| D  | 8.650       | 9.800  | 0.341     | 0.386 |
| d1   | 15.88       | 16.120 | 0.622     | 0.635 |
| d3   | 12.300      | 12.920 | 0.484     | 0.509 |
| E  | 10.360      | 10.630 | 0.408     | 0.419 |
| e  | 2.54 BSC    |        | 0.100 BSC |       |
| L  | 13.200      | 13.730 | 0.520     | 0.541 |
| L1   | 3.100       | 3.500  | 0.122     | 0.138 |
| n  | 6.050       | 6.150  | 0.238     | 0.242 |
| Ø P  | 3.050       | 3.450  | 0.120     | 0.136 |
| u  | 2.400       | 2.500  | 0.094     | 0.098 |
| v  | 0.400       | 0.500  | 0.016     | 0.020 |
| ECN: X09-0126-Rev. B, 26-Oct-09<br>DWG: 5972 |             |        |           |       |

**Notes**

1. To be used only for process drawing.
2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
3. All critical dimensions should C meet  $C_{pk} > 1.33$ .
4. All dimensions include burrs and plating thickness.
5. No chipping or package damage.

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